

FIGURE 1A

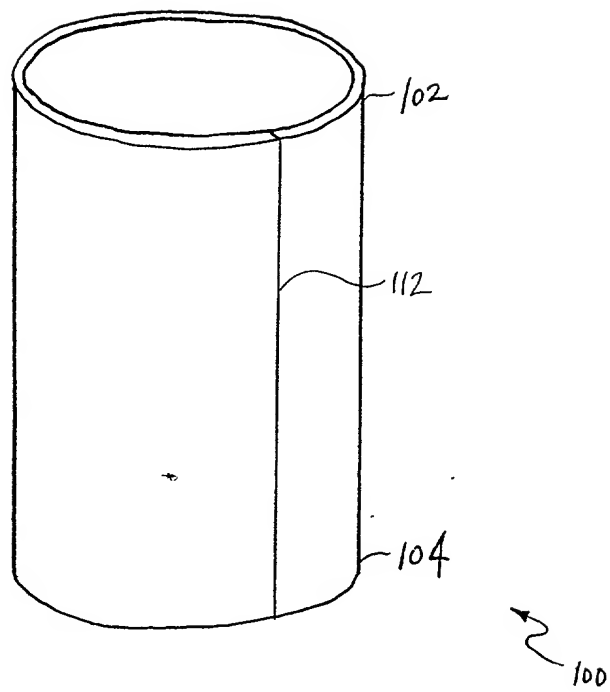


FIGURE 1B

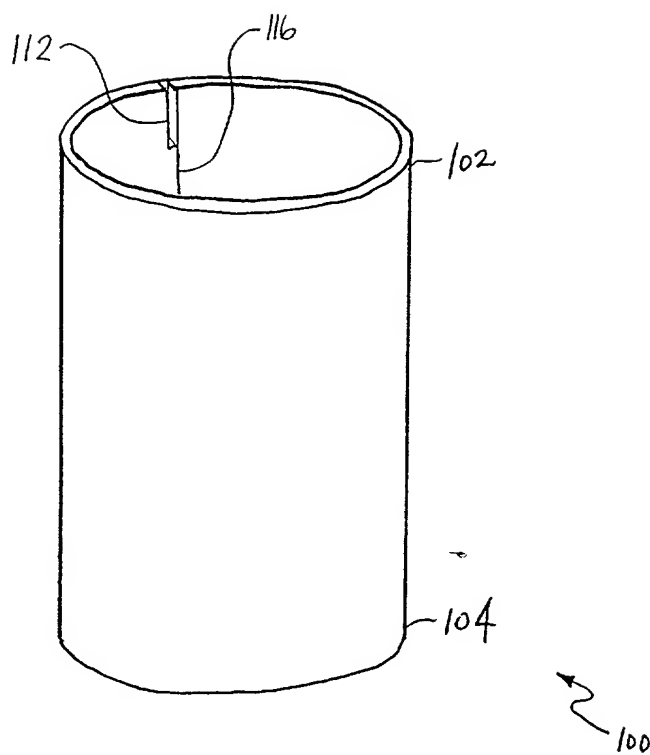


FIGURE 1C

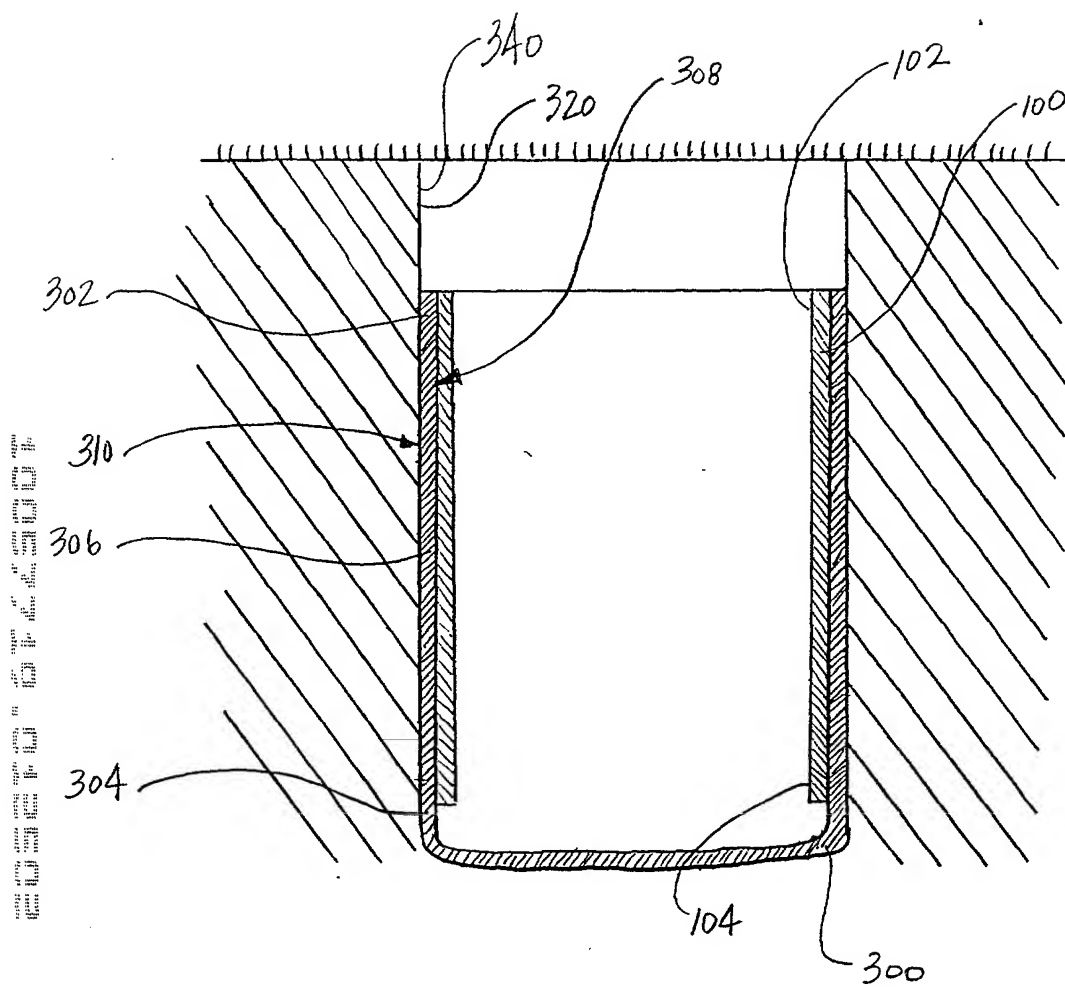


FIGURE 2A

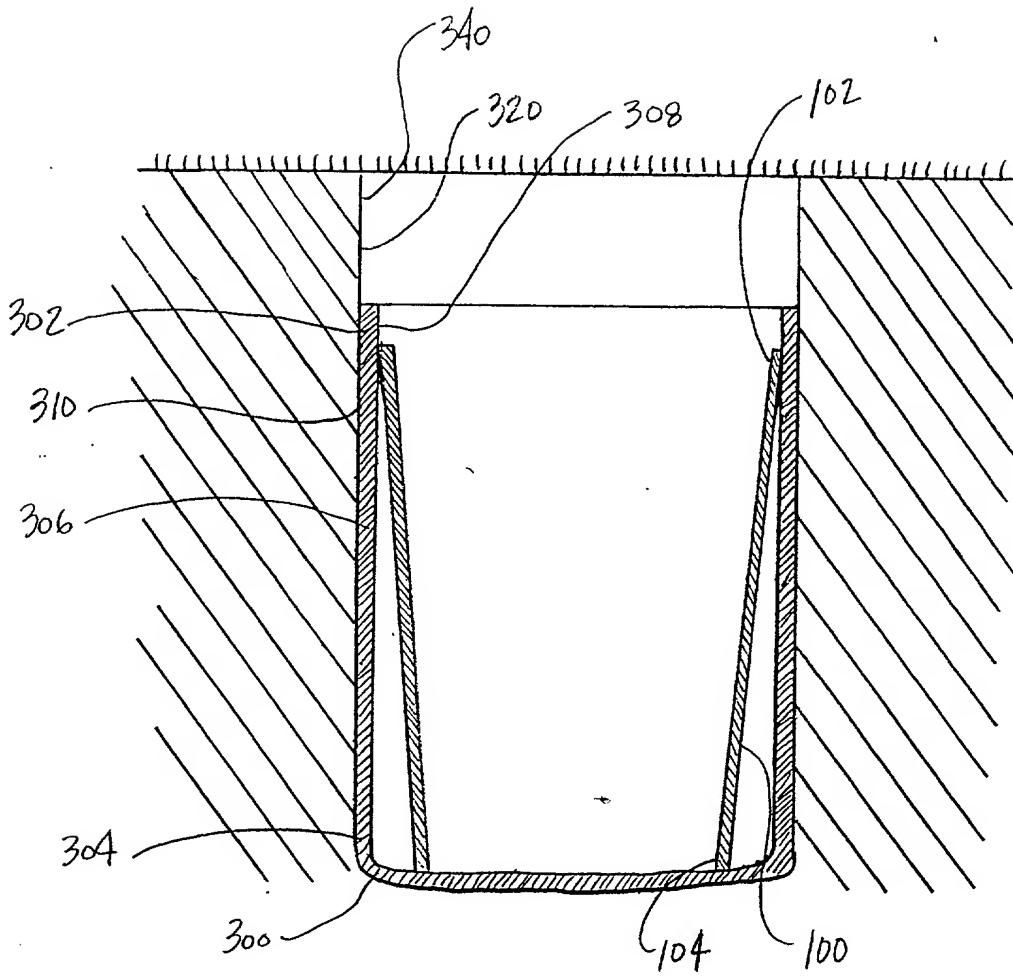


FIGURE 2B

FIG. 3 is a cross-sectional view of a device 100, showing a substrate 102 with a layer 104. A structure 300 is formed on the substrate 102, including a layer 302, a layer 310, a layer 306, a layer 308, and a layer 304. A feature 340 is shown in the structure 300, and a feature 320 is shown in the substrate 102.

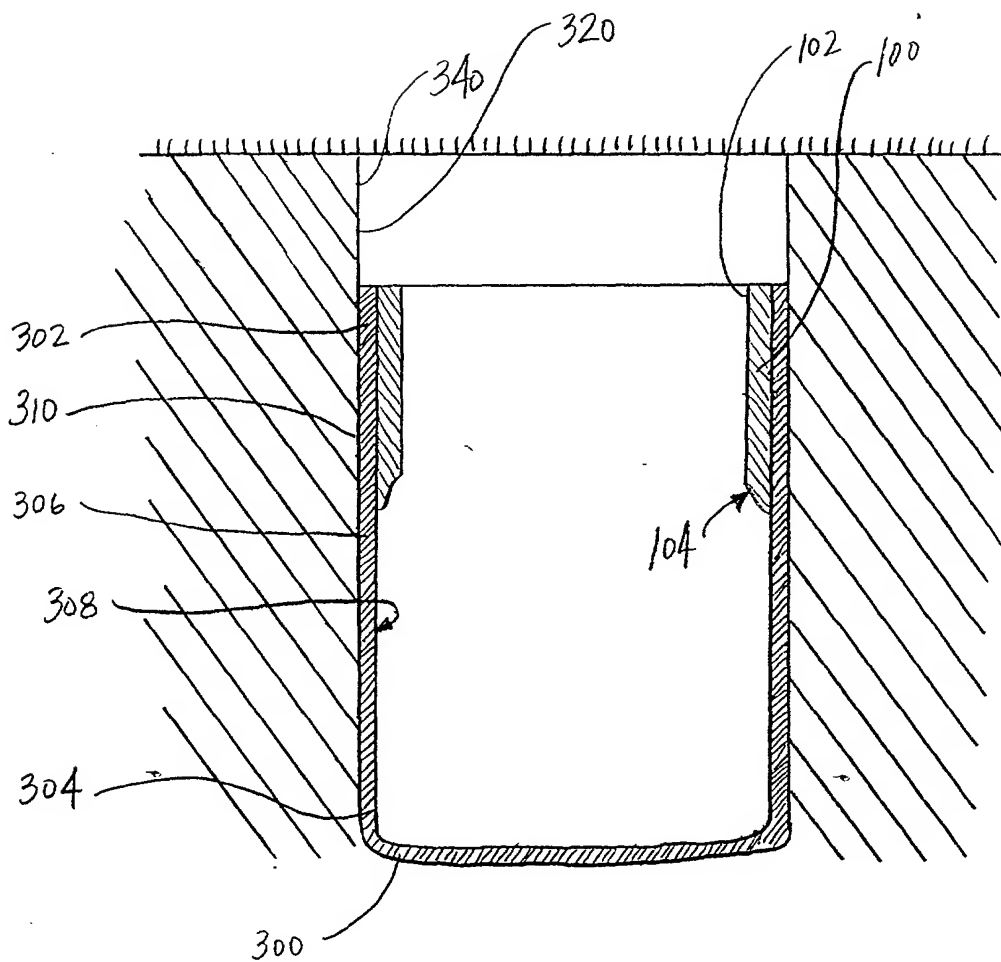


FIGURE 3

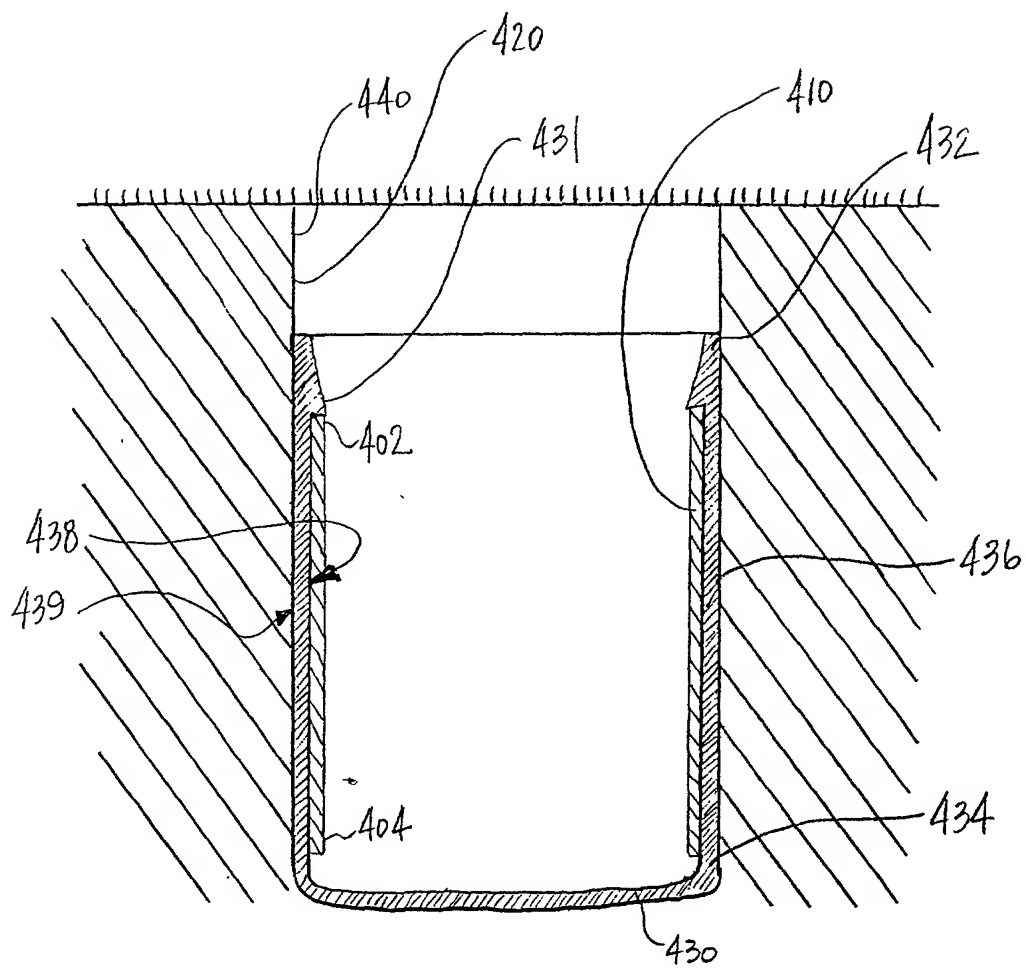


FIGURE 4

400

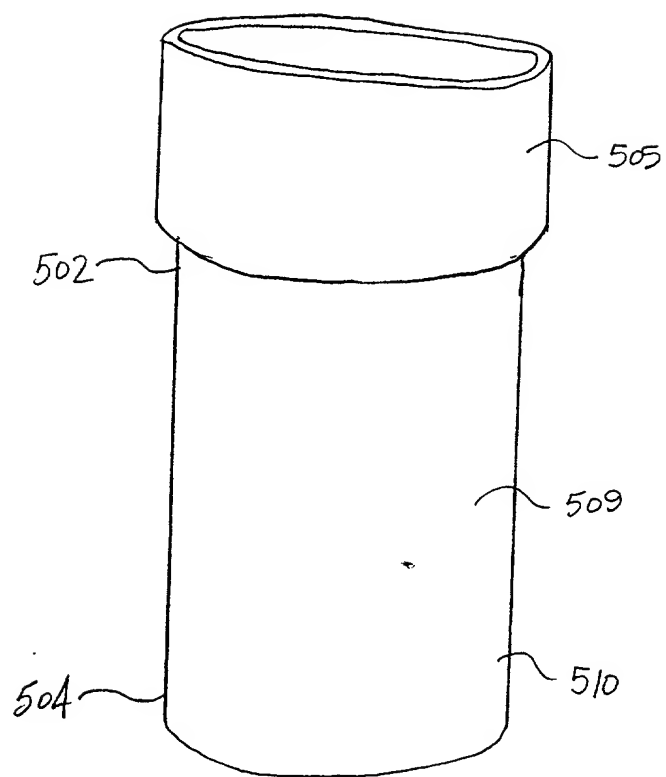


FIGURE 5



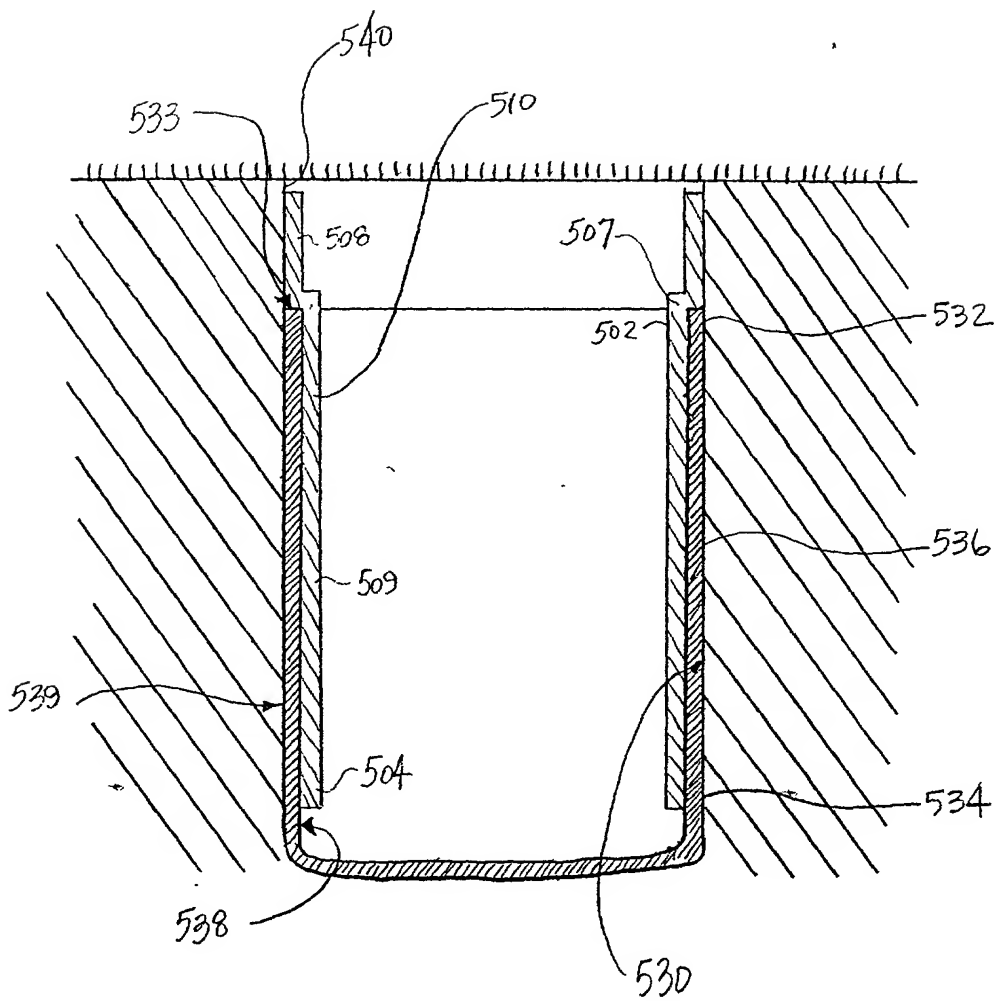


FIGURE 6